

**AMENDMENTS TO THE SPECIFICATION**

Please insert the following section headings on amended page 1, after the title and at line 3:

-- BACKGROUND OF THE INVENTION

1) Field of the Invention --

Please replace the paragraph on amended page 1, beginning at line 4, with the following replacement paragraph:

-- The present invention relates to a device for encapsulating an electronic component according to the preamble of claim 1. The invention also relates to a method for encapsulating with encapsulating material an electronic component, in particular a semiconductor, fixed on a carrier.--

Please insert the following section heading on amended page 1, at line 8:

-- 2) Description of the Related Art --

Please insert the following section heading on amended page 2, at line 1:

-- SUMMARY OF THE INVENTION --

Please replace the paragraph on amended page 2, beginning at line 2, with the following replacement paragraph:

-- The invention provides for this purpose a device according claim 1. This provides a structurally simple device. Although a displaceable component (the support) still also has to be accommodated in the mould part with the projecting edge, this component is less critical than the displaceable component in the mould part according to the prior art since it does not have to come into contact with the encapsulating material. The connection of the displaceable support to the associated mould part may have a free intermediate space because the encapsulating material flows over the projecting edge onto the carrier; the displaceable support plays no part in this phase (at the position where the encapsulating material flows onto the board or earlier during the route covered by the encapsulating material in the liquid phase). Compensation of possible variations in thickness of different carriers is possible by means of the proposed construction. Not only lead frames of metal, composite lead frames of synthetic resin and/or ceramic among other materials, but also lead frames of thinner foil can for instance be processed

with the device according to the invention. Another very relevant advantage compared to the prior art is that ~~is that~~ the chance of undesirable delamination can be reduced considerably. Yet another advantage of the present invention is that it enables the positioning of the carrier in the mould part before it is urged to the projecting edge as the sides of the mould part that surround the support are stationary parts of the mould part and due to their stable position, this in contrast with the closest prior art, highly reliable in their positioning. The present construction with stationary reference sides also enable the loading, positioning and off loading of the carriers from various sides. It is for instance possible to bring the carrier in, or to move it out, from the contact side of the mould part. In this case care has to be taken that the carrier is given an extra movement to bring it partially under the projecting edge. Alternatively it is also possible to bring the carrier in, or to move it out, parallel to the contact side of the mould part. This means sliding the carrier in or out the mould part directly under the projecting edge, making an extra movement for final positioning superfluous. --

Please replace the paragraph on amended page 4, beginning at line 19, with the following replacement paragraph:

-- The invention also provides a method for encapsulating with encapsulating material an electronic component, in particular a semiconductor, fixed on a carrier, ~~according claim 8~~. By means of this method the advantages can be realized as already described above with reference to the device according to the present invention. --

Please replace the paragraph on amended page 4, beginning at line 24, with the following replacement paragraph:

-- The feed of the liquid encapsulating material ~~according to step D)~~ is herein at least partially defined by the projecting edge of the first mould part. This defining can means direct defining of the projecting edge on the encapsulating material but also an indirect defining (i.e. via for instance foil material). The application of foil material is however not essential in practice. --

Please replace the paragraph on amended page 4, beginning at line 30, and continuing onto amended page 5, with the following replacement paragraph:

-- After a processing step D), the encapsulating material will cure ~~during a processing step E)~~. This then makes it possible in a preferred variant of the method for the carrier with encapsulating

material arranged thereon to be displaced relative to the projecting edge such that a cured strip of encapsulating material leading from the projecting edge to the carrier is broken by the displacement. It is desirable for this purpose that the carrier be displaced relative to the projecting edge in the direction of the part of the first mould part supporting the carrier. The projecting edge functions here as a cutting edge along which the separation is made in the (partially) cured encapsulating material. Alternatively, it is also possible for the carrier to be rotated relative to the projecting edge so as to thus make a separation in the encapsulating material. --

Please replace the paragraph on amended page 5, beginning at line 13, with the following replacement paragraph:

-- In a particular embodiment variant of the method according to the invention, after closing a second mould part onto the first mould part ~~as according to processing step C)~~, the mould parts are moved apart a distance of 1 to 50  $\mu\text{m}$ , where after the distance between the projecting edge and the part of the first mould part supporting the carrier is then reduced such that a part of the carrier is clamped with a controllable force between the part of the first mould part supporting the carrier and the projecting edge. In this preferred variant the closing force of the mould parts is no longer of any significance for the result of the sensitive clamping as applied in accordance with this preferred variant of the method. Another advantage is that very pressure-sensitive carriers (for instance of ceramic or soft materials such as foil material) can also be processed in this manner without notable problems. --

Please insert the following section heading on amended page 5, at line 24:

-- BRIEF DESCRIPTION OF THE DRAWINGS --

Please insert the following section heading on amended page 6, at line 3:

-- DETAILED DESCRIPTION OF THE PREFERRED EMBODIMENTS --